Abstracts

3D microwave modules for space applications

P. Monfraix, P. Ulian, C. Drevon, S. George, A.C. Vera, C. Tronche, J.L. Cazaux, O. Llopis and J. Graffeuil. "3D microwave modules for space applications." 1998 MTT-S International Microwave Symposium Digest 98.3 (1998 Vol. III [MWSYM]): 1289-1292.

This paper describes the design, manufacturing and measurement of 3D microwave modules. The vertical interconnection between stacked circuits is based on an shielded homogeneous coplanar line with a 90/spl deg/ vertical structure. The fabrication of these modules is in relation with the "MultiChip Module Vertical" technology, originally developed for digital applications. The electrical measurement in the Ku-band demonstrates very good results.

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